



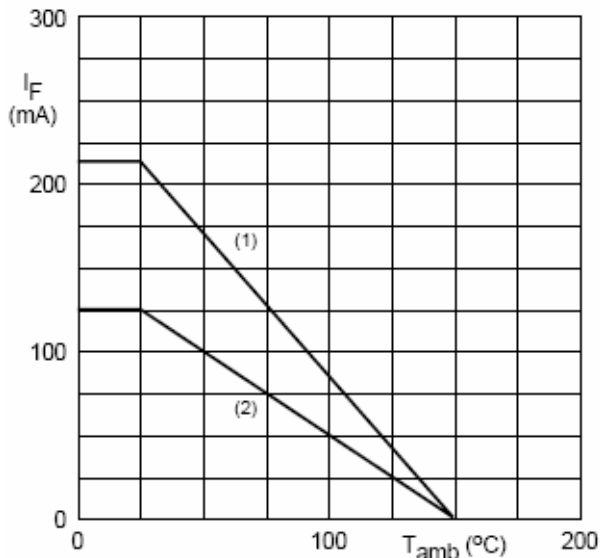
Low-leakage double diode

BAV170

ELECTRICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified

Characteristic	Symbol	Typ	MAX	UNIT	Test Condition
Forward Voltage	V_F		900 1000 1100 1250	mV	$I_F=1\text{mA}$ $I_F=10\text{mA}$ $I_F=50\text{mA}$ $I_F=150\text{mA}$
Reverse Leakage Current	I_R	0.003 3	5 80	nA	$V_R=75\text{V}$ $V_R=75\text{V}, T_J=150^\circ\text{C}$
Junction Capacitance	C_j	2		pF	$V_R=0\text{V}, f=1.0\text{MHz}$
Reverse Recovery Time	t_{rr}	0.8	3	μs	$I_F=I_R=10\text{mA}, I_{rr}=0.1 \cdot I_R$

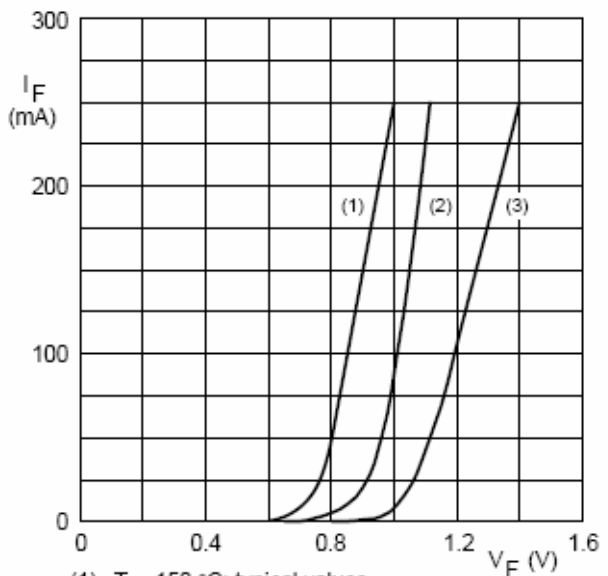
TYPICAL CHARACTERISTICS @ Ta=25°C unless otherwise specified



Device mounted on a FR4 printed-circuit board.

- (1) Single diode loaded.
- (2) Double diode loaded.

Maximum permissible continuous forward current as a function of ambient temperature.

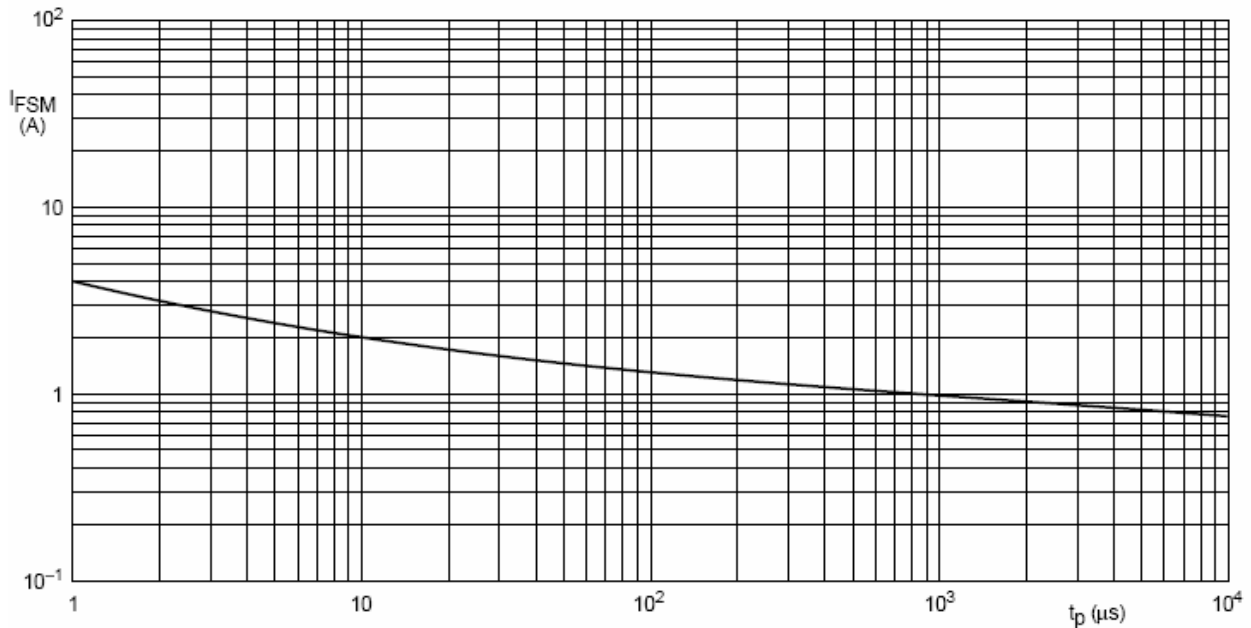


- (1) $T_j = 150^\circ\text{C}$; typical values.
- (2) $T_j = 25^\circ\text{C}$; typical values.
- (3) $T_j = 25^\circ\text{C}$; maximum values.

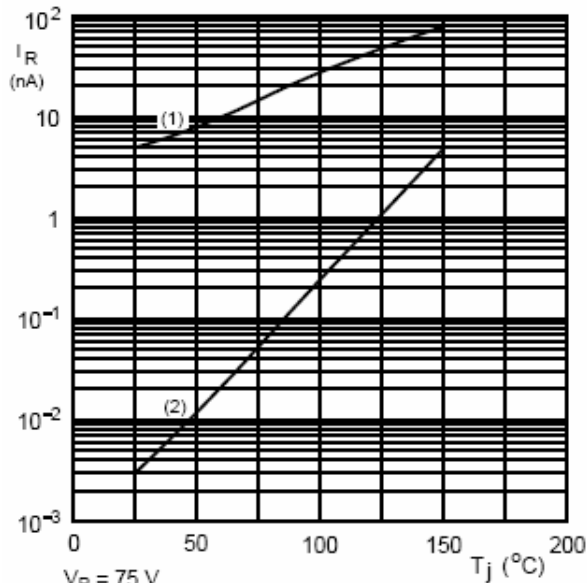
Forward current as a function of forward voltage; per diode.

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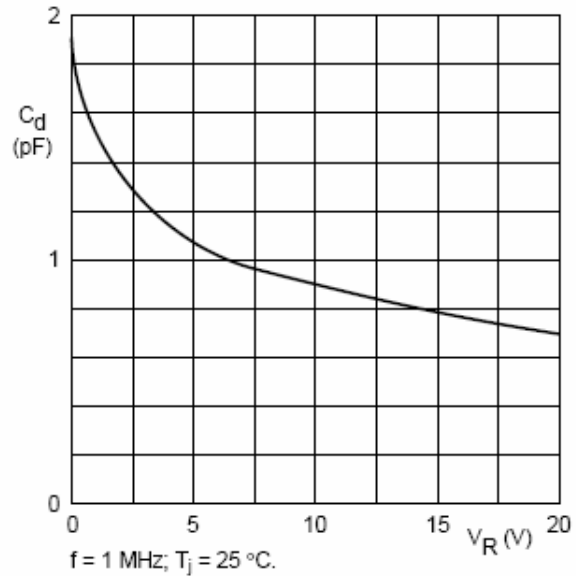
Maximum permissible non-repetitive peak forward current as a function of pulse duration per diode.



$V_R = 75$ V.

- (1) Maximum values.
- (2) Typical values.

Reverse current as a function of junction temperature; per diode.



Diode capacitance as a function of reverse voltage; per diode; typical values.

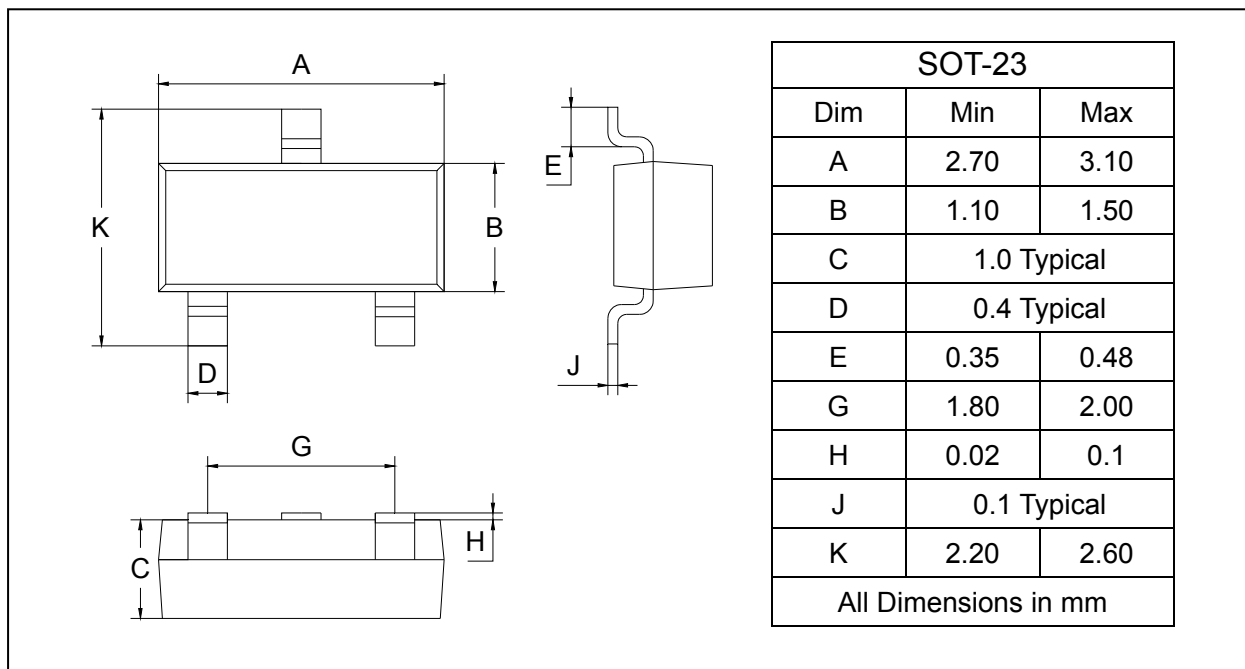
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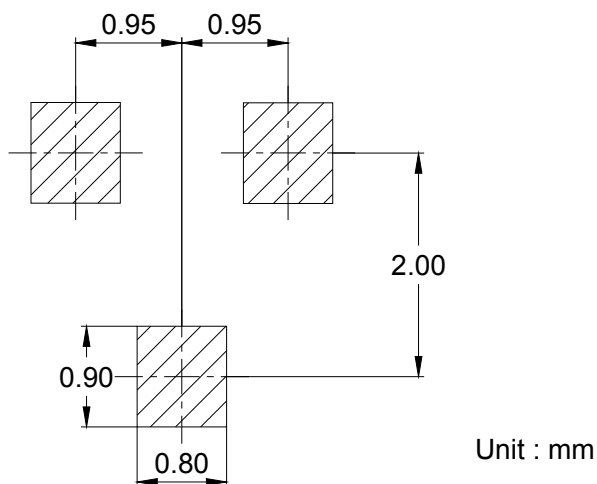
PACKAGE OUTLINE

Plastic surface mounted package

SOT-23



SOLDERING FOOTPRINT



PACKAGE INFORMATION

Device	Package	Shipping
BAV170	SOT-23	3000/Tape&Reel